



NOEL Technologies

LITHOGRAPHY READY RESIST SPIN COATINGS

Resist Type	Full Thickness Range	Wave Length
TARF 6111	1600A - 3000A	193nm
TARF 7052	4500 - 7200A	193nm
SPR955	7000A - 12000A	365nm
UV210-0.3	4500A - 7200A	248nm
S1811	19000A - 35000A	365nm
UV 6-0.8	10000A - 20000A	248nm
SPR 3012	19000A - 35000A	365nm
SPR 220-3	45000A - 85000A	365nm
SPR 220-7	90000A - 140000A	365nm
Plating Resists		
SPIR 9272-6	65000 - 95000A	365nm
SPIR 9272-10	10000 - 140000A	365nm
Az125nXT	200000A - 1200000A	365nm
Lift-Off Resists		
AZ nLOF2020	34000A - 58000A	365nm
AZ nLOF2035	57000A - 100000A	365nm

Thickness Ranges on 300mm Diameter Wafers

Noel validates the resist thickness via optical metrology on silicon wafers on resist thickness less than 10um.

On resist thickness >10um a step height measurement is taken on silicon wafers to verify the thickness. Thickness Tolerance $\pm 2\%$.

Lithography Ready Resist Spin Coatings Process Includes: Prime/Coat/Soft Bake